

LISTING OF CLAIMS:

1. (Currently amended) A pressure sensitive adhesive sheet, comprising a base material and a pressure sensitive adhesive layer in which a plurality of through holes passing through one face to the other face are formed, wherein

the hole diameter of the through holes at the base material and the pressure sensitive adhesive layer is 0.1 to 300 μm ,

the hole diameter of the through holes at a front surface of the pressure sensitive adhesive sheet is 40 μm or less, and

the hole density is 30 to 50,000/100 cm^2 ,

the through holes are formed by a laser beam machining, and

the base material comprises a resin film made of ~~polyolefin, polyester, polyvinyl chloride~~ or polyurethane.

2-9. (Canceled)

10. (Previously presented) The pressure sensitive adhesive sheet according to claim 1, wherein the base material is transparent, and the hole diameter of the through hole in the base material and the pressure sensitive adhesive layer is 0.1 to 60 μm .

11. (Canceled)

12. (Previously presented) The pressure sensitive adhesive sheet according to claim 1 or claim 11, wherein the hole diameter of the through holes gradually decreases from a back surface to a front surface of the pressure sensitive adhesive sheet.

13. (New) A pressure sensitive adhesive sheet, comprising a base material and a pressure sensitive adhesive layer in which a plurality of through holes, which pass through the pressure sensitive adhesive sheet from one face of the pressure sensitive adhesive sheet to an opposite face of the pressure sensitive adhesive sheet, are formed, wherein

the hole diameter of the through holes at the base material and the pressure sensitive adhesive layer is 0.1 to 300 μm ,

the hole diameter of the through hole at the surface of the pressure sensitive adhesive sheet is 40 μm or less,

the hole density is 30 to 50,000/100 cm^2 , the through holes are formed by a laser beam machining, and

the base material comprises a resin film made of polyolefin.

14. (New) A pressure sensitive adhesive sheet, comprising a base material and a pressure sensitive adhesive layer in which a plurality of through holes, which pass through the pressure sensitive adhesive sheet from one face of the pressure sensitive adhesive sheet to an opposite face of the pressure sensitive adhesive sheet, are formed, wherein

the hole diameter of the through holes at the base 15 material and the pressure sensitive adhesive layer is 0.1 to 300 μm ,

the hole diameter of the through hole at the surface of the pressure sensitive adhesive sheet is 40 μm or less,

the hole density is 30 to 50,000/100 cm^2 ,

the through holes are formed by a laser beam machining, and

the base material comprises a resin film made of polyester.